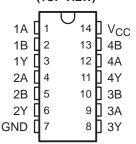
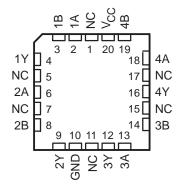
- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V

SN54ACT32...J OR W PACKAGE SN74ACT32...D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Max t_{pd} of 10 ns at 5 V
- Inputs Are TTL-Voltage Compatible

SN54ACT32 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'ACT32 devices are quadruple 2-input positive-OR gates. The devices perform the Boolean function Y = A + B or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

ORDERING INFORMATION

TA	PACKAGI	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	SN74ACT32N	SN74ACT32N	
	0010 P	Tube	SN74ACT32D	4.0700	
	SOIC - D	Tape and reel	SN74ACT32DR	ACT32	
-40°C to 85°C	SOP - NS	Tape and reel	SN74ACT32NSR	ACT32	
	SSOP – DB	Tape and reel	SN74ACT32DBR	AD32	
	TOOOD DW	Tube	SN74ACT32PW	4500	
	TSSOP – PW	Tape and reel	SN74ACT32PWR	AD32	
	CDIP – J	Tube	SNJ54ACT32J	SNJ54ACT32J	
–55°C to 125°C	CFP – W	Tube	SNJ54ACT32W	SNJ54ACT32W	
	LCCC - FK	Tube	SNJ54ACT32FK	SNJ54ACT32FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Χ	Н
X	Н	Н
L	L	L



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logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Note 1)		–0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$).		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	-	±50 mA
Continuous current through V _{CC} or GND		±200 mA
Package thermal impedance, θ _{JA} (see Note 2)	: D package	86°C/W
	DB package	96°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{sta}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		SN54ACT32		SN74A	CT32	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	in	2		V
VIL	Low-level input voltage		0.8		8.0	V
VI	Input voltage	0	Vcc	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	V
ЮН	High-level output current	ng	-24		-24	mA
loL	Low-level output current	08	24		24	mA
Δt/Δν	Input transition rise or fall rate	7	8		8	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS	vcc	T _A = 25°C			SN54ACT32		SN74ACT32		
PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Jan. 50 nA	4.5 V	4.4			4.4		4.4		
	$IOH = -50 \mu A$	5.5 V	5.4			5.4		5.4		
V	Jan. 24 mA	4.5 V	3.86			3.7		3.76		.,
Voн	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		V
	I _{OH} = -50 mA [†]	5.5 V				3.86				
	$I_{OH} = -75 \text{ mA}^{\dagger}$						EN	3.85		
	I _{OL} = 50 μA	4.5 V		0.001	0.1		0.1		0.1	V
		5.5 V		0.001	0.1	.<	0.1		0.1	
V	I _{OL} = 24 mA	5.5 V			0.36	Ź	0.5		0.44	
VOL		5.5 V			0.36	g	0.5		0.44	
	I _{OL} = 50 mA [†]	5.5 V				y.	1.65			
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40		20	μΑ
Δl _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V		0.6			1.6		1.5	mA
C _i	V _I = V _{CC} or GND	5 V		2.6					·	pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\,\pm\,$ 0.5 V (unless otherwise noted) (see Figure 1)

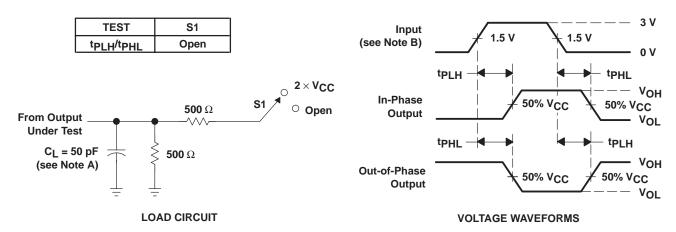
FROM		то	T _A = 25°C		SN54ACT32	SN74ACT32			
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
t _{PLH}	A or B	V	1	6.5	9	SEOFAIL	1	10	no
^t PHL	AUID	ſ	1	6.5	9	Sk.	1	10	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST C	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	40	pF

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





ti.com 18-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ACT32D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT32DBLE	OBSOLETE	SSOP	DB	14		None	Call TI	Call TI
SN74ACT32DBR	ACTIVE	SSOP	DB	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT32DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ACT32NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT32PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ACT32PWLE	OBSOLETE	TSSOP	PW	14		None	Call TI	Call TI
SN74ACT32PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

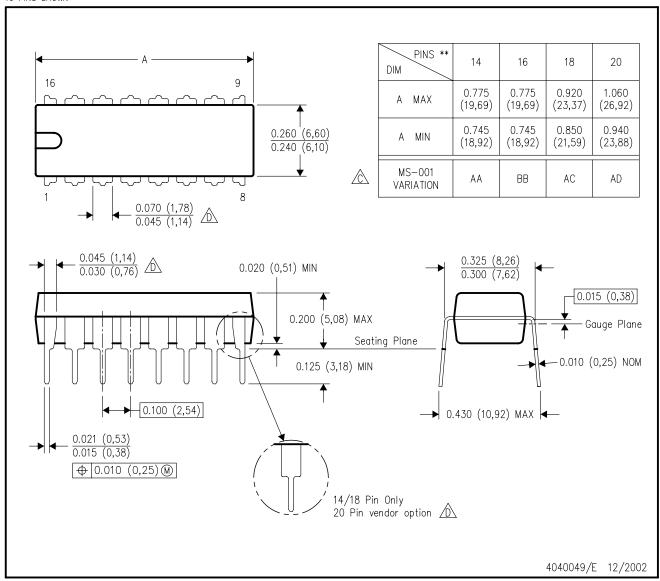
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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



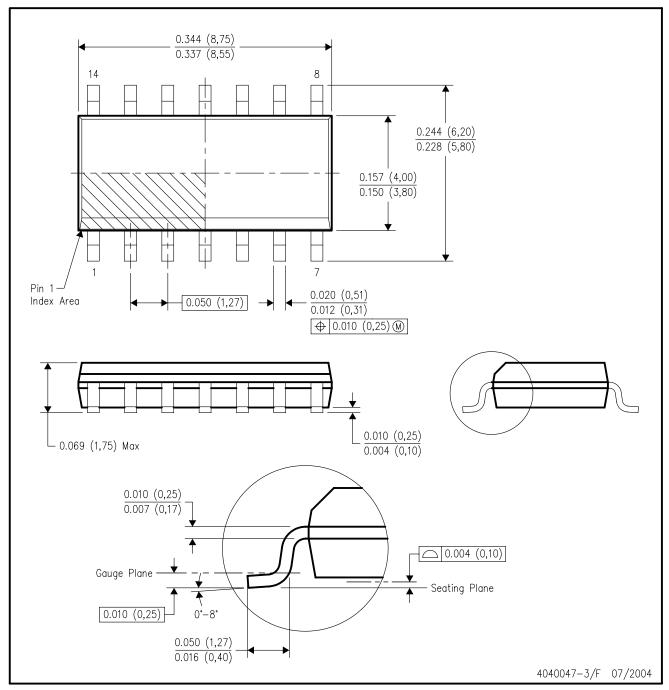
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.

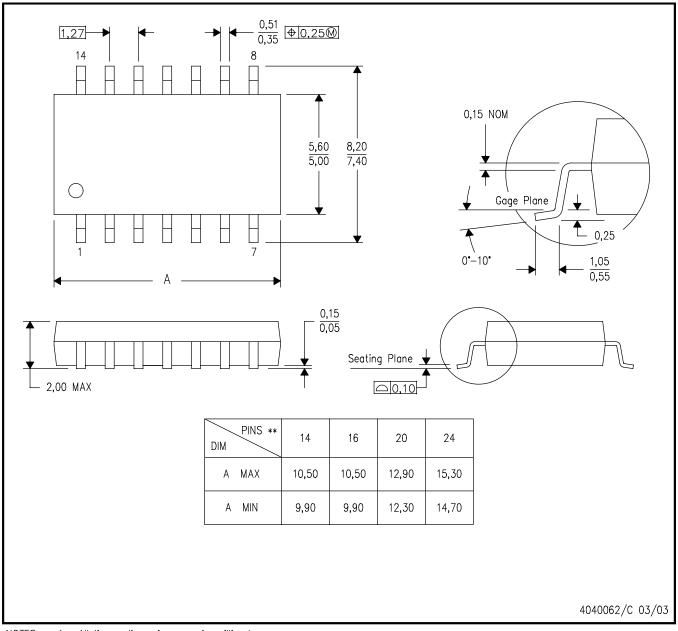


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

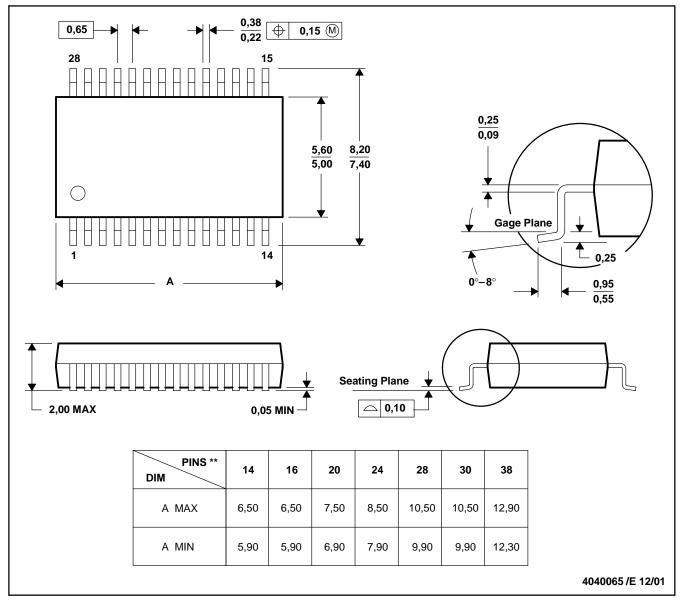
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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